

General Description

The 60R190Q is power MOSFET using Cmos's advanced super junction technology that can realize very low on-resistance and gate charge. It will provide much high efficiency by using optimized charge coupling technology. These user friendly devices give an advantage of Low EMI to designers as well as low switching loss.

Features

- Multi-layer Epitaxial Chip Technology
- Low On-Resistance
- 100% avalanche tested
- RoHS Compliant

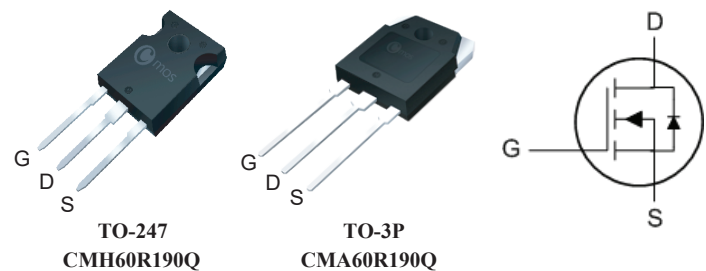
Product Summary

BVDSS	R _{DS(on)} max.	ID
600V	0.199Ω	20A

Applications

- Charger
- Adaptor
- Power Supply

TO-3P/TO-247 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	600	V
V _{GS}	Gate-Source Voltage	±30	V
I _D @T _C =25°C	Continuous Drain Current	20	A
I _D @T _C =100°C	Continuous Drain Current	14	A
I _{DM}	Pulsed Drain Current (Note 1)	80	A
EAS	Single Pulse Avalanche Energy (Note 2)	633	mJ
P _D @T _C =25°C	Total Power Dissipation	250	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient (Note 3,4)	---	75	°C/W
R _{θJC}	Thermal Resistance Junction-case	---	0.50	°C/W

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	600	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V$, $I_D=9.5A$	---	---	0.199	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	2	---	4	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=600V$, $V_{GS}=0V$	---	---	1	μA
		$V_{DS}=600V$, $T_C=150^{\circ}\text{C}$	---	10	---	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 30V$, $V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=15V$, $I_D=10A$	---	15	---	S
R_g	Gate Resistance	$V_{DS}=0V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	8.4	---	Ω
Q_g	Total Gate Charge	$I_D=20A$	---	36	---	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=480V$	---	9	---	
Q_{gd}	Gate-Drain Charge	$V_{GS}=10V$	---	14	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=300V$ $V_{GS}=10V$ $I_D=20A$ $R_G=25\Omega$	---	24	---	ns
T_r	Rise Time		---	89	---	
$T_{d(off)}$	Turn-Off Delay Time		---	212	---	
T_f	Fall Time		---	68	---	
C_{iss}	Input Capacitance	$V_{DS}=100V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	1430	---	pF
C_{oss}	Output Capacitance		---	75	---	
C_{rss}	Reverse Transfer Capacitance		---	6.5	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	20	A
I_{SM}	Pulsed Source Current		---	---	80	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V$, $I_S=20A$, $T_J=25^{\circ}\text{C}$	---	0.90	1.4	V
t_{rr}	Reverse Recovery Time	$di/dt=100A/\mu s$	---	347	---	ns
Q_{rr}	Reverse Recovery Charge	$V_{DD}=100V$, $I_{SD}=20A$	---	5.3	---	μC

Notes:

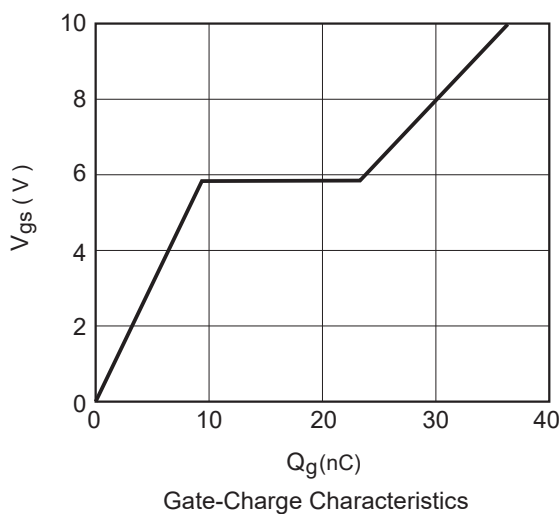
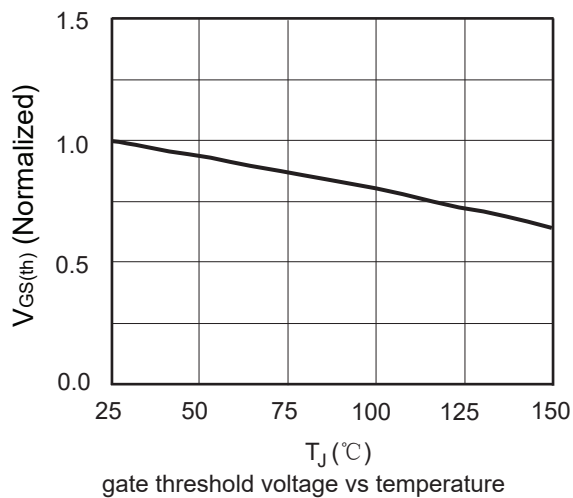
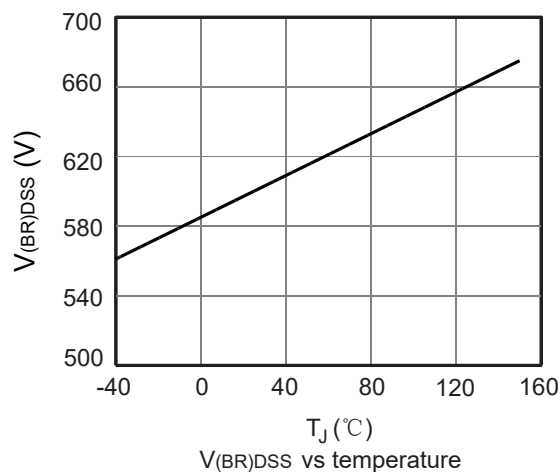
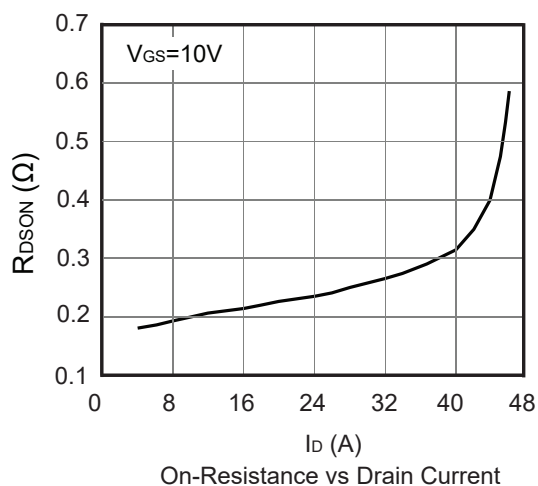
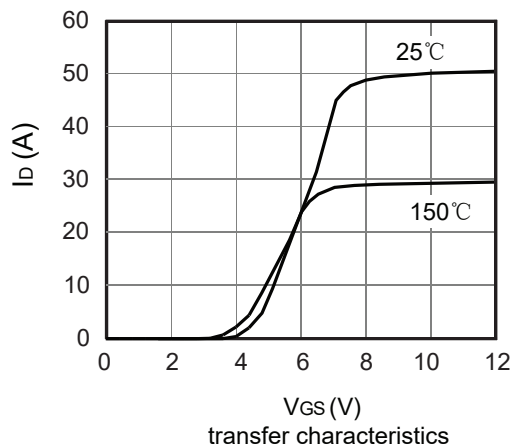
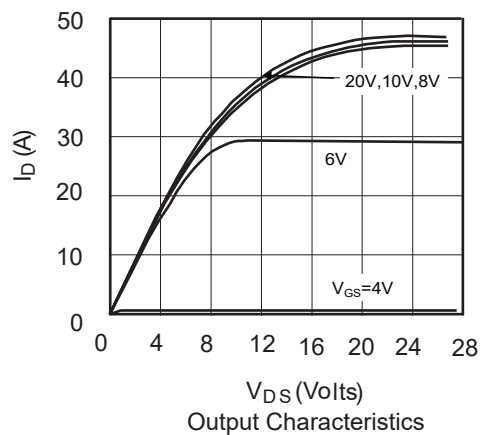
1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. $L=30\text{mH}$, $I_{AS}=6.5A$, $V_D=100V$, Starting $T_J=25^{\circ}\text{C}$.
3. The value of $R_{\theta JA}$ is measured with the device in a still air environment with $T_A=25^{\circ}\text{C}$.
4. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.

This product has been designed and qualified for the consumer market.

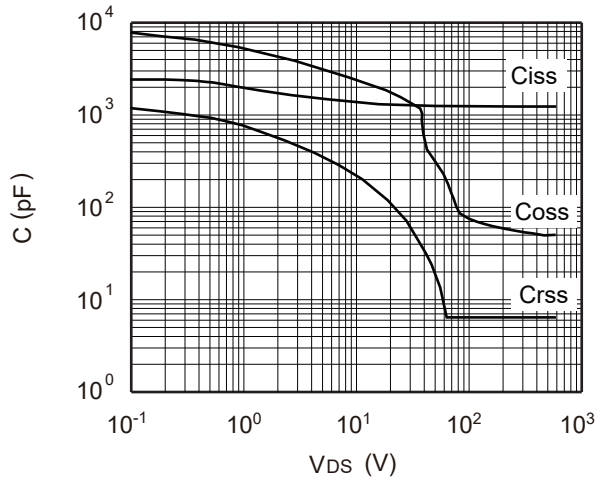
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Cmos reserves the right to improve product design ,functions and reliability without notice. Please refer to the latest version of specification.

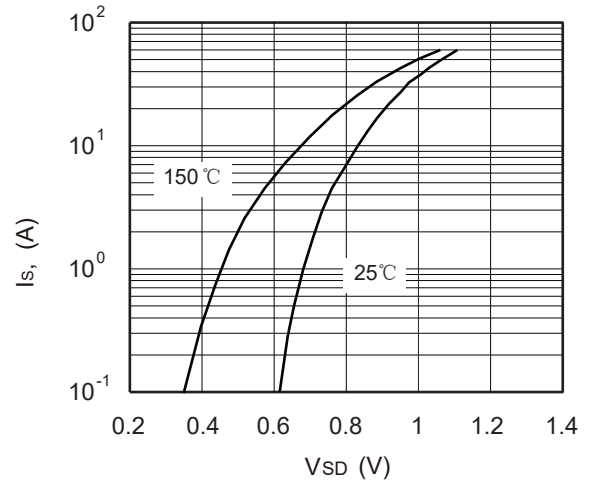
Typical Characteristics



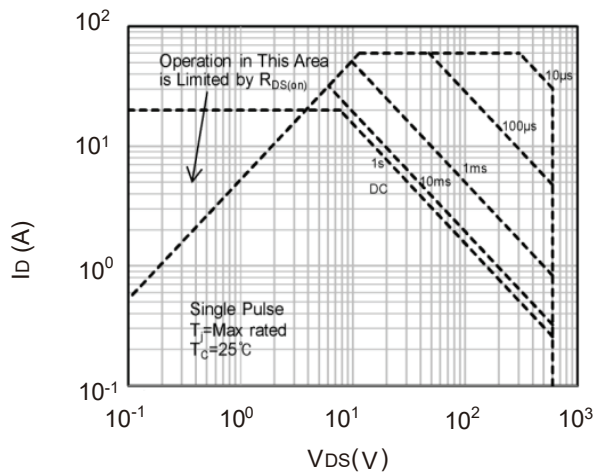
Typical Characteristics



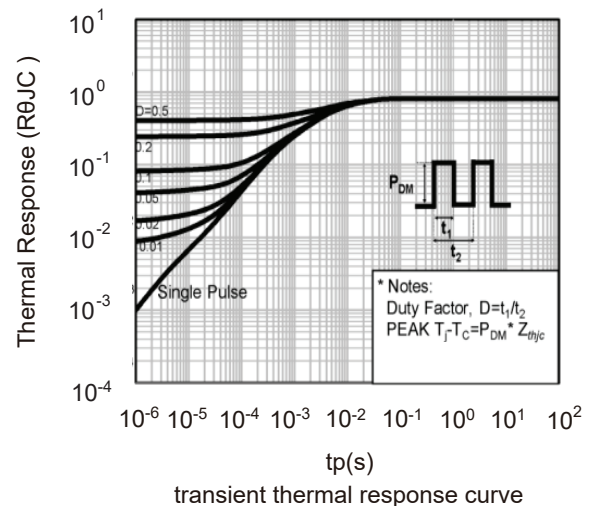
Capacitance Characteristics



Body-Diode Characteristics



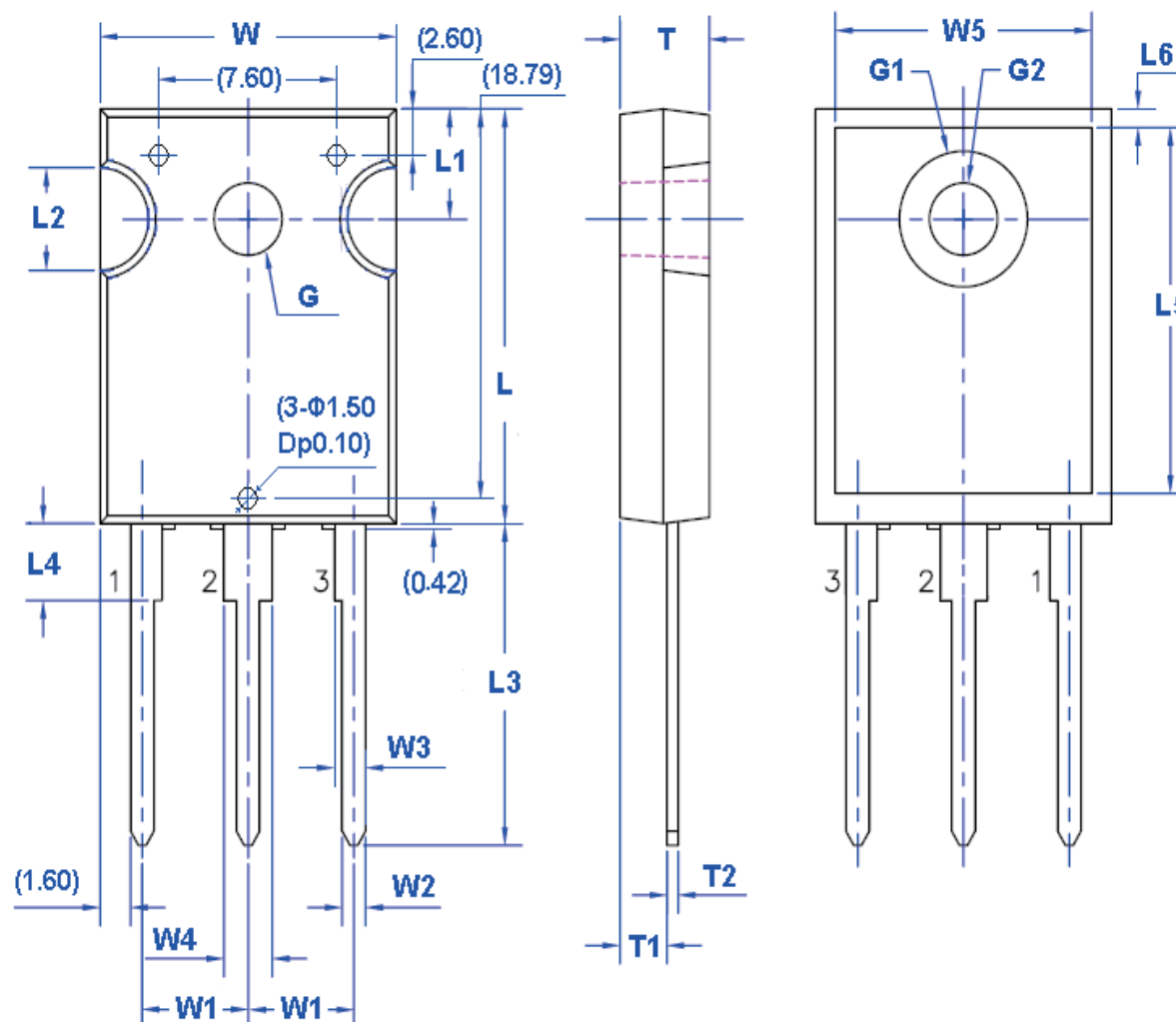
Safe operating area



transient thermal response curve

Package Dimensions

TO-247 Package Outline Drawing



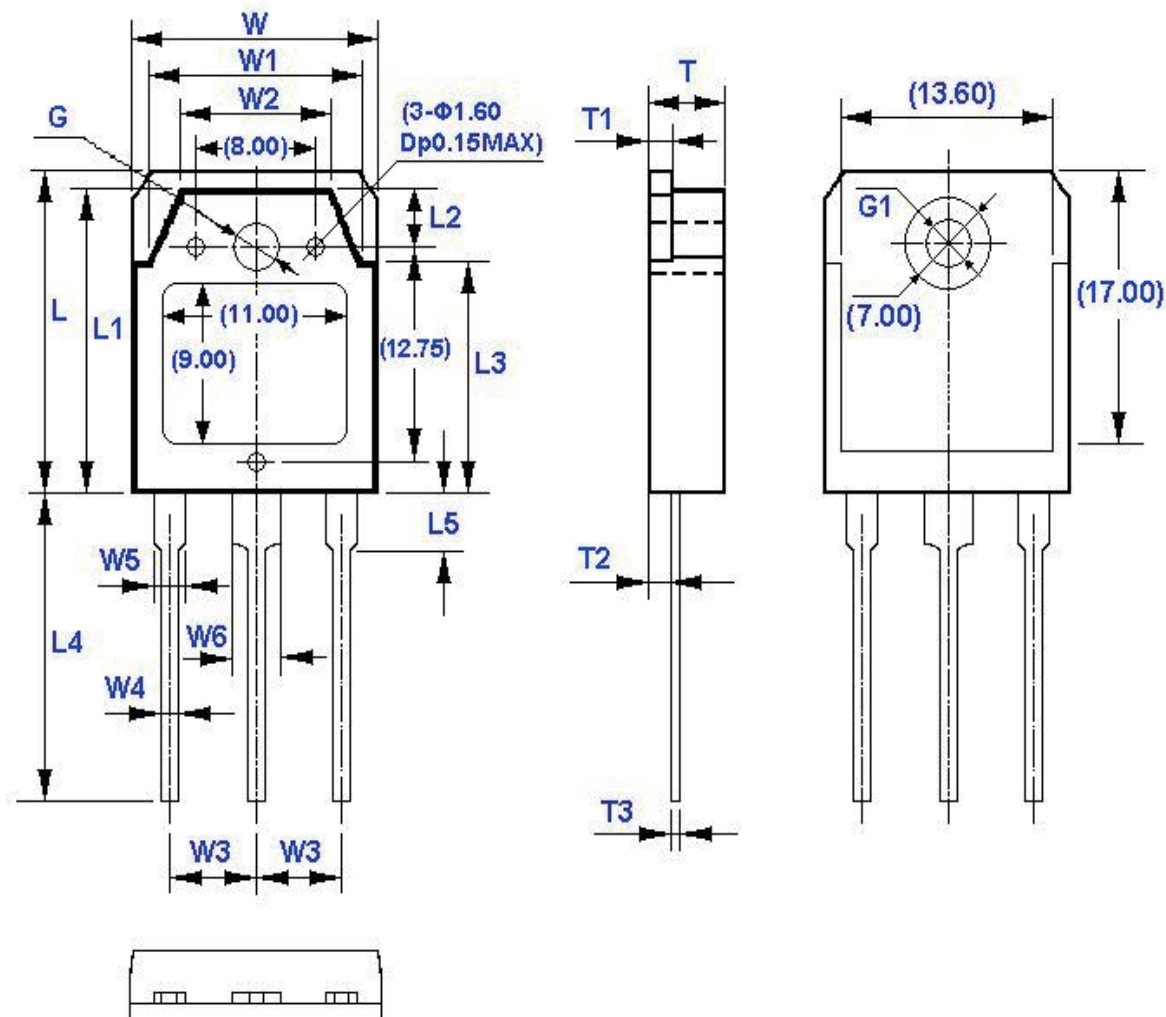
(Unit : mm)

Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	15.37	15.87	W5	12.70	13.00	L4	3.69	3.93	T2	0.51	0.71
W1	5.56 (TYP)		L	20.32	20.82	L5	16.00	17.00	G(Φ)	3.51	3.65
W2	1.17	1.35	L1	5.34	5.58	L6	0.51	1.35	G1(Φ)	6.61	6.85
W3	1.53	1.77	L2	4.96	5.20	T	4.58	4.82	G2(Φ)	3.51	3.65
W4	2.42	2.66	L3	15.75	16.25	T1	2.29	2.66			

Note: The values in () are reference values. Size does not include burrs and mold flash

Package Dimensions

TO-3P Package Outline Drawing



(Unit : mm)

Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	15.40	15.80	W5	1.80	2.20	L3	13.70	14.10	T2	1.20	1.60
W1	13.40	13.80	W6	2.80	3.20	L4	19.70	20.30	T3	0.55	0.75
W2	9.40	9.80	L	19.70	20.10	L5	3.30	3.70	G (Φ) (front)	3.30	3.50
W3	5.45 (TYP)		L1	18.50	18.90	T	4.60	5.00	G1(Φ) (back)	3.10	3.30
W4	0.80	1.20	L2	3.60	4.00	T1	1.45	1.65			

Note: The values in () are reference values. Size does not include burrs and mold flash